

ABSTRACT OF THE DISCLOSURE

An integrated circuit package structure having an array of metal pegs connected by printed circuit lines. The package includes a die pad having a die positioned above and an area array distribution of external metal pegs surrounding the die. The package 5 also contains a plurality of internal metal pegs that surround the die. These internal pegs are electrically connected to the bonding pads on the die via conductive medium. The die pad, the die, the conductive medium and the internal pegs are all enclosed by an insulating material. The bottom side of the die pad is exposed while the external metal pegs are electrically connected to various internal metal pegs using printed circuit lines.

10 Furthermore, an electroplate layer is also formed on the end face of each metal peg.